	Application No.	Applicant(s)	
ALC: CAU LIVE.	10/051,890	CONNELL ET AL.	
Notice of Allowability	Examiner	Art Unit	
	Mark A Osele	1734	
The MAILING DATE of this communication appears on the cover sheet with the correspondence address All claims being allowable, PROSECUTION ON THE MERITS IS (OR REMAINS) CLOSED in this application. If not included herewith (or previously mailed), a Notice of Allowance (PTOL-85) or other appropriate communication will be mailed in due course. THIS NOTICE OF ALLOWABILITY IS NOT A GRANT OF PATENT RIGHTS. This application is subject to withdrawal from issue at the initiative of the Office or upon petition by the applicant. See 37 CFR 1.313 and MPEP 1308.			
1. This communication is responsive to <u>amendment filed August 9, 2004</u> .			
2. The allowed claim(s) is/are <u>11-23,25,26 and 50-57</u> .			
3. The drawings filed on 15 April 2002 are accepted by the Examiner.			
 4. Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f). a)			
 Attachment(s) 1. ☑ Notice of References Cited (PTO-892) 2. ☐ Notice of Draftperson's Patent Drawing Review (PTO-948) 3. ☑ Information Disclosure Statements (PTO-1449 or PTO/SB/O Paper No./Mail Date 08092004 4. ☐ Examiner's Comment Regarding Requirement for Deposit of Biological Material 	5. Notice of Informal P 6. Interview Summary Paper No./Mail Dat 7. Examiner's Amendr 8. Examiner's Stateme 9. Other	(PTO-413), te ment/Comment	

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REASONS FOR ALLOWANCE

The following is an examiner's statement of reasons for allowance: Newly cited references to Koopmans, Tan et al., and Sturcken et al. each show stacked microelectronic devices wherein the top device is adhesively bonded to the lower device with adhesive that does not cover the entire lower face of the top device. None of the references is prior art, however, against the instant invention and none of the references shows the claimed method of applying the adhesive to the rear surface of a semiconductor wafer, defining a plurality of adhesive pads within the adhesive layer, and singulating the wafer into individual microelectronic components.

It is further noted that the previously cited reference to Jiang et al. is also not prior art against the instant invention.

Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably accompany the issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for Allowance."

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Mark A Osele whose telephone number is 571-272-1235. The examiner can normally be reached on Mon-Fri 9:30-6:00.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Christopher Fiorialla can be reached on 571-272-1178.

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The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

MARK A. OSELE PRIMARY EXAMINER August 21, 2004